



# 100% Material Declaration Data Sheet for 7 Series CL484 Package

PK772 (v1.0) November 13, 2015

**Average Weight: 1.1360 g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.025878</b>	<b>2.278</b>
	Silicon	7440-21-3	100.00		0.025878	
<b>Die Attach Material</b>					<b>0.008105</b>	<b>0.713</b>
	Silver	7440-22-4	77.50		0.006281	
	Bismaleimide monomer	Trade Secret	15.00		0.001216	
	Acrylate monomer	Trade Secret	7.50		0.000608	
<b>Mold Compound</b>					<b>0.476919</b>	<b>41.981</b>
	Epoxy Resin	Trade secret	5.00		0.023846	
	Phenol Resin	Trade secret	3.00		0.014308	
	Phenol Novolac	9003-35-4	3.00		0.014308	
	Metal Hydroxide	Trade Secret	3.00		0.014308	
	Carbon black	1333-86-4	0.30		0.001431	
	Silica fused	60676-86-0	70.40		0.335751	
	Silica Dioxide	7631-86-9	15.00		0.071538	
Silica, crystalline	14808-60-7	0.30		0.001431		
<b>Copper Wire</b>					<b>0.006315</b>	<b>0.556</b>
	Copper	7440-50-8	98.20		0.006201	
	Palladium	7440-05-3	1.80		0.000114	
<b>Solder Ball</b>					<b>0.233980</b>	<b>20.596</b>
	Tin	7440-31-5	63.00		0.147407	
	Lead	7439-92-1	37.00		0.086573	
<b>Substrate</b>					<b>0.384804</b>	<b>33.872</b>
	Gold	7440-57-5	0.21		0.000808	
	Nickel	7440-02-0	1.22		0.004695	
	Copper	7440-50-8	44.30		0.170468	
	Glass Fiber	65997-17-3	21.20		0.081578	
	Non halogen fire retardant	Trade Secret	0.01		0.000038	
	BT Core	105391-33-1/ 25722-66-1/ Trade Secret	25.91		0.099703	
Solder Mask	34590-94-8/ 7727-43-7/ Trade Secret	7.17		0.027590		

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## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
11/13/2015	1.0	Xilinx Initial Release

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